



SY22812

High Frequency QR Flyback Controller with Valley Lockout and E-mode GaN FET Driver

General Description

SY22812 is a high frequency QR Flyback controller targeting at PD adaptors and fast charges. SY22812 can drive enhancement GaN FET directly. It is suitable for wide output voltage range application, with maximum 240W output power. Maximum switching frequency can be up to 500kHz, so size of transformer and capacitors can be reduced.

In normal QR Flyback solutions, valley number always jumps between 1-2 or 3-5, which will increase V_o ripple and bring audio noise. SY22812 can lock valley with proprietary circuit and valley number can be 1 to 6th. System state is more stable than normal QR solutions.

SY22812 works under peak current mode. It adopts QR mode and GaN FET can be turned on at valley point to reduce switching loss, especially under high input voltage. If load decreases more, SY22812 will enter DCM to reduce switching frequency for higher efficiency. If load is very light, SY22812 will enter burst mode to reduce power loss.

SY22812 also provides comprehensive and reliable functions including HV startup, X-cap discharge, brown out protection, output OVP and UVP, OLP, VCC OVP, internal and external OTP, etc.

SY23434 is recommended to be used as secondary side SR controller in conjunction with SY22812. Then ZVS operation can be achieved for higher efficiency.

SY22812 is available with SSOP9.

Ordering Information

SY22812□(□□□)

Package Code
Optional Spec Code

Ordering Number	Package Type	Note
SY22812FVP	SSOP9	-----

Features

- DCM+QR Combined Operating Mode
- Adaptive OCP (LPS, Limited Power Source)
- Direct E-mode GaN FET Driver
- Programmable Gate Driver Current
- 140V LDO in VCCH pin
- Switching Frequency Range: 25kHz~500kHz
- Valley Lockout from 1 to 6th
- Low Frequency Burst (1kHz)
- Frequency Modulation to Reduce EMI Noise
- Internal Soft Start
- Integrated 700V HV Start up
- Brown In/Out Protection
- X-cap Discharge Protection
- Programmable Output OVP&UVP
- Current Sense Resistor Short Protection
- Internal & External OTP
- Compact Package: SSOP9

Applications

- AC-DC Adaptors
- PD Adaptors
- Quick Chargers

Typical Applications

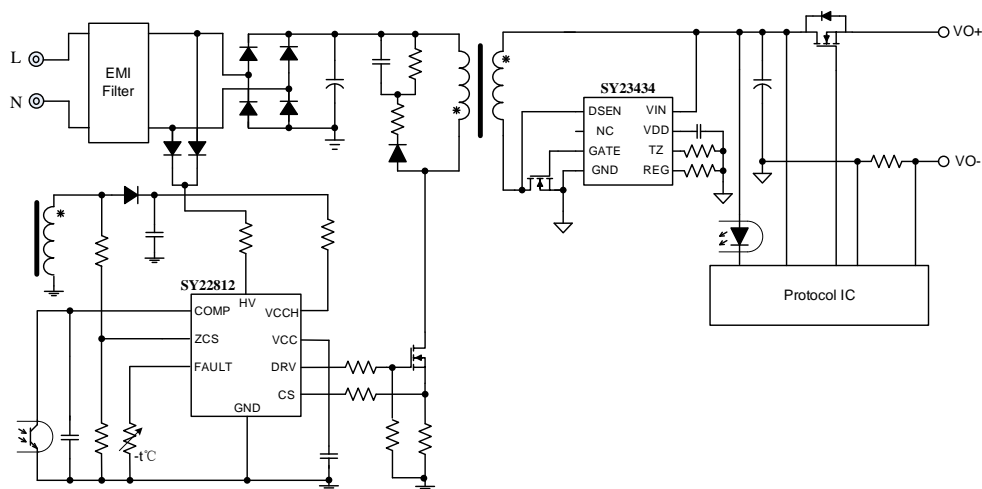
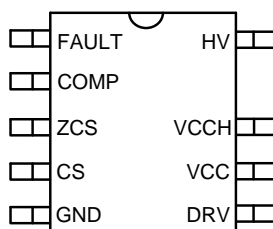


Figure 1. Typical Application Circuit

Pinout (top view)



(SSOP9)

Top Mark: GMMxyz (Device code: GMM; x=year code, y=week code, z= lot number code)

Pin Name	Pin Description
FAULT	External OTP and Vout OVP pin.
COMP	Compensation voltage of secondary side, connected to an opto-coupler.
ZCS	Output voltage, input voltage and QR valley detection pin.
CS	Inductor current sensing pin.
GND	Ground pin.
DRV	Programmable GaN FET gate drive pin.
VCC	Power supply pin.
VCCH	High voltage power supply pin.
HV	HV startup, Brown in/out, X-cap discharge detection pin.

Absolute Maximum Ratings (Note 1)

HV	-----	-0.3V to 700V
VCC	-----	-0.3V to 30V
VCCH	-----	-0.3V to 140V
DRV	-----	-0.3V to 8V
CS, COMP, FAULT	-----	-0.3V to 4V
ZCS	-----	-1V ^(Note1) to 7V
Power Dissipation, @ T _A = 25°C SSOP9	-----	0.79W
Package Thermal Resistance (Note 2)		
SSOP9, θ_{JA}	-----	158°C/W
SSOP9, θ_{JC}	-----	30°C/W
Junction Temperature Range	-----	-40°C to 150°C
Lead Temperature (Soldering, 10 sec.)	-----	260°C
Storage Temperature Range	-----	-60°C to 150°C
Note1, Dynamic ZCS negative voltage in 50us Duration	-----	-1V
Note1, Dynamic ZCS negative current in 50us Duration	-----	-2mA

Recommended Operating Conditions

HV	-----	-0.3V to 700V
VCC	-----	8V to 25V
VCCH	-----	9V to 140V
DRV	-----	4V to 6V
CS	-----	-0.3V to 0.5V
ZCS	-----	-0.3V to 3.0V
COMP	-----	-0.3V to 2.5V
FAULT	-----	-0.3V to 3.0V
Junction Temperature Range	-----	-40°C to 125°C
Case Temperature Range	-----	-40°C to 105°C

Block Diagram

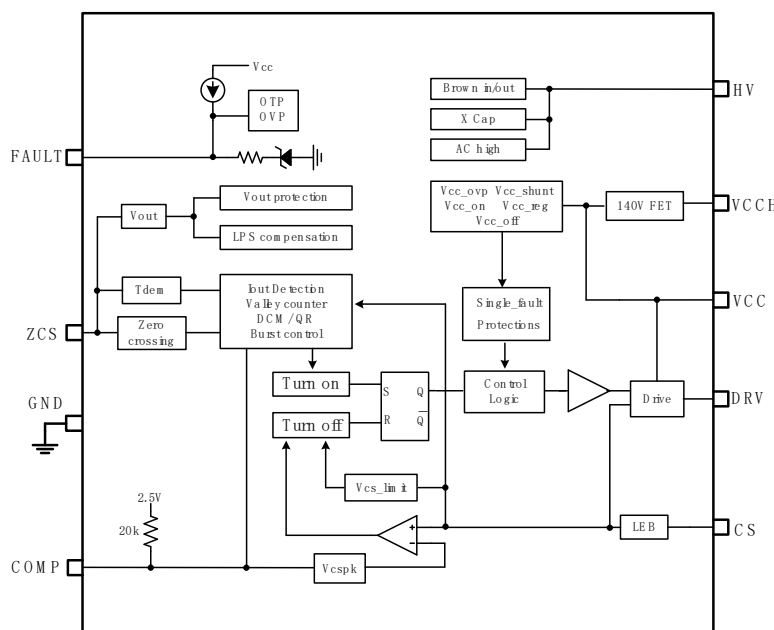


Fig.2 Block Diagram

Electrical Characteristics

(V_{CC} = 13V (Note 3), T_A = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
HV Pin Section						
HV Current to Charge VCC	I _{HV_CHARGE1}	V _{HV} = 100V _{DC} , V _{CC} = 0V	0.15	0.3	0.55	mA
		V _{HV} = 100V _{DC} , V _{CC} = 3V	2.6	4.0	5.4	mA
Current to Discharge X Cap	I _{HV_XCAP}			2.0		mA
High or Low Voltage Detection	HV _{th_AChigh}		200	218	236	V
AC Low Debounce Time	T _{AClow_DBC}			20		ms
Debounce Time to Detect AC Unplug	T _{UNPLUG_DBC}			100		ms
BO Threshold	HV _{th_BO}		89	95	103	V
BI Threshold	HV _{th_BI}			105		V
BO Debounce Time	T _{BO_DBC}			100		ms
BI Debounce Time	T _{BI_DBC}			200		μs
VCC Pin Section						
VCC Turn-on Threshold	V _{CC_ON}	V _{CC} rising	18	20	22	V
VCC Turn-off Threshold	V _{CC_OFF}	V _{CC} falling	6.5	7.0	7.5	V
VCC Short Threshold	V _{CCSHORT_TH}		0.5	0.7	0.8	V
VCCH Regulation Threshold	V _{CC_REG}		10	11	12	V
VCCH Regulation Hysteresis	V _{CC_REGHYS}			1.0		V
Protection Timer after Error Trigger	T _{ERROR}			1.0		s
VCC OVP Threshold	V _{CC_OVP}	V _{VCC} rising	26.4	28.0	29.6	V
VCC OVP Debounce Cycles	N _{VCCOVP_DBC}			4		
VCC Shunt Threshold	V _{CC_SHUNT}		25	27	29	V
VCC Shunt Current Capability	I _{VCC_SHUNT}	V _{CC} > V _{CC_SHUNT}		10		mA
Normal Operation Current Consumption	I _{CC_OPERATING}	C _L = open, F _{sw} = 50kHz		1.2		mA
Standby Current Consumption	I _{CC_STANDBY}	V _{COMP} < V _{TH_SLEEP_IN}	280	400	520	μA
VCCH Pin Section						
Maximum Voltage	VCCH _{BV}		140			V
CS Pin Section						
Maximum Peak Current Limit Threshold if Secondary Side Short	V _{CS_MAX}		685	720	755	mV
Leading Edge Blanking for V _{cs_max}	T _{CS_LEB1}			150		ns
Delay Time from V _{cs_max} to PWM off	T _{CSMAX_DELAY}			30		ns
V _{cs_max} Debounce Cycles	N _{VCSMAX_DBC}			4		
V _{cs} Limit	V _{CS_limit}		475	500	525	mV
OCP Threshold for Normal Option (Note 4)	V _{REF_OCPNORMAL}		530	555	580	mV
OCP High Threshold for LPS Option (Note 5)	V _{REF_OCPLPSH}	V _{ZCS} < V _{ZCSLPS_LOW}	730	770	810	mV
OCP Low Threshold for LPS Option (Note 5)	V _{REF_OCPLPSL}	V _{ZCS} > V _{ZCSLPS_HIGH}	425	450	480	mV
Leading Edge Blanking Time for V _{pk} Control and V _{cs_limit}	T _{CS_LEB2}			250		ns
Delay Time from V _{cs_limit} to DRV Falling	T _{CS_DELAY2}			30		ns

Delay time from Vpk control to DRV Falling	T _{CS_DELAY3}			30		ns
Vcs Min in DCM Mode	V _{CSMIN_DCM}		65	80	95	mV
Debounce Time of I _{OUT} OCP	T _{IOUTOCP_DBC}			200		ms
Soft Start Time	T _{SST}			10		ms
Frequency of Modulation in QR Mode	F _{MODULATION_QR}			4		kHz
Vcspk Modulation Amplitude in QR Mode	V _{QR_MODULATION1}	Valley=1~3		20		mV
		Valley=4~6		30		mV
CS Short Circuit Protection	V _{CS_SHORT}	Ton=4μs		60		mV
ZCS Pin Section						
OVP Threshold Voltage	V _{ZCS_OVP}		2.36	2.50	2.64	V
OVP Threshold Voltage Debounce Cycles	N _{ZCSOVP_DBC}			4		
UVP Threshold Voltage of Vout	V _{ZCS_UVP}			150		mV
UVP Threshold Voltage Debounce Time	T _{VOUTUVP_DBC}			20		ms
Maximum Value of off Blanking Time	T _{ZCSLEB_MAX}		1.3	1.80	2.3	μs
Minimum Value of off Blanking Time	T _{ZCSLEB_MIN}		0.5	0.7	1	μs
Maximum off Time	T _{OFF_MAX}		90	120	150	μs
Zero Cross Point Detect	V _{ZCS_ZERO}			0		mV
QR Turn on Delay Time	T _{ZCS_ONDELAY}			100		ns
LPS Compensation High Point	V _{ZCSLPS_HIGH}		1.74	1.90	1.98	V
LPS Compensation Low Point	V _{ZCSLPS_LOW}		1.06	1.12	1.24	V
Fault Pin Section						
Current Source for OTP Detection	I _{OTP}		46.5	49	51.5	μA
OTP Threshold	V _{OTP_TH}		0.37	0.4	0.43	V
OTP Exit Threshold	V _{OTPEXIT_TH}			0.9		V
Clamp Diode for OVP	V _{OVPDIODE}		1.45	1.7	1.95	V
Capability of Clamp Diode for OVP	I _{FAULTOVP}			1		mA
OVP Threshold	V _{OVP_TH}			2.5		V
Debounce Time to Trigger OTP/OVP	T _{FAULTOTP/OVP_DBC}	V _{FAULT} <V _{OTP_TH} V _{FAULT} >V _{OVP_TH}		100		μs
COMP pin section						
Internal Pull up Voltage Source	V _{COMP_PULLUP}		2.2	2.5	2.8	V
Internal Pull up Resister	R _{COMP_PULLUP}			20		kΩ
Vcs_limit Point	V _{COMP_LIMIT}			1.9		V
QR Mode to DCM Change Threshold	V _{COMPTH_DCM}			1.0		V
Hysteresis of QR Mode to DCM	V _{COMPTH_DCMHYS}			0.1		V
Minimum Switching Frequency Threshold	V _{COMP_FMIN}		0.55	0.7	0.85	V
Enter Burst Mode Threshold	V _{COMP_BURSTIN}	V _{COMP} falling	0.19	0.25	0.31	V
Exit Burst Mode Threshold	V _{COMP_BURSTOUT}	V _{COMP} increasing		0.45		V
Start PWM Threshold in Burst Mode	V _{COMP_BURSTSTART}	V _{COMP} increasing		0.35		V
Burst Frequency	V _{COMP_BURSTFREQ}			1		kHz
OLP Threshold	V _{COMP_OLP}	V _{COMP} rising	1.95	2.2	2.45	V
OLP Debounce Time	T _{OLP_DBC}	V _{COMP} > V _{TH,OLP}		50		ms
DRV Pin Section						

High Voltage Clamp	V _{DRV-CS_CLAMP}		5.5	5.8	6.1	V
Programmable Driver Current	I _{DRV}	DVR-GND: 43kohm		5		mA
		DVR-GND: 22kohm		10		mA
		DVR-GND: 10kohm		20		mA
		DVR-GND: <2kohm		Error		
Sink Current	I _{DRV_SINK}			600		mA
Ton_max	T _{ON_MAX}		14	20	26	μs
Frequency Limit in DCM Mode.	F _{LIMIT_DCM}			75		kHz
Frequency Min in DCM Mode	F _{MIN_DCM}		20	25	32	kHz
Frequency of Modulation in DCM Mode	F _{MODULATION_DCM}			250		Hz
Minimum Valley Number in QR Mode	VALLEY _{NUMBER}	HV<218V	1			
		HV>218V	2			
Internal OTP						
OTP Threshold	T _{OVP_SHUTDOWN}			150		°C
Recovery Threshold	T _{OVP_RECOVERY}			130		°C

Note 1: Stresses beyond the “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note 2: θ_{JA} is measured in the natural convection at $T_A = 25^{\circ}\text{C}$ on a low effective single layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard. Test condition: Device mounted on “2 x 2” FR-4 substrate PCB, 2oz copper, with minimum recommended pad on top layer and thermal via to bottom layer ground plane.

Note 3: Increase VCC pin voltage gradually higher than VCC_ON voltage then turn down to 13V.

Note 4: Normal OCP option is selected by ZCS pin resistor.

Note 5: LPS OCP option is selected by ZCS pin resistor.

Note 6: Selection of ZCS resistors is as follows.

ZCS pull down	Xcap function	Iout_ocr
25-27kOhm $\pm 1\%$	Disabled.	Normal Option
13.0kOhm $\pm 1\%$	Enabled.	Normal Option
7.5kOhm $\pm 1\%$	Disabled.	LPS Option
3.0-3.6kOhm $\pm 1\%$	Enabled.	LPS Option

ZCS_ovp threshold is 2.50V. When pull down resistor is determined, pull up resistor can be calculated according to Vout_ovp and Na/Ns. Then CS pin's in series resistor should be adjusted too. If Iout_ocr increases according to Vac's rising, value of CS pin's in series resistor should be increased for more compensation.

Operation Principles

HV start up and power supply

HV pin charges Vcc capacitor at AC power on. When Vcc voltage rises to start up threshold and HV will stop charging. Internal circuit of HV pin will be turned off for lower standby loss.

At start up, HV will charge Vcc pin and VCCH pin together at AC power on. VCCH's capacitor may be 10uF and Vcc's capacitor can be as less as 1uF, which is convenient to PCB layout.

In protection mode, SY22812 will stop PWM for T_{ERROR}. During T_{ERROR}, SY22812 has current consumption and Vcc(VCCH) capacitor cannot hold for so long time. When Vcc falls to Vcc_{reg}, HV will charge Vcc(VCCH) again until Vcc > (Vcc_{reg} + Vcc_{reghys}). After T_{ERROR}, internal logic will be reset for restart.

QR mode (Valley number is 1-6)

In QR mode, PWM turns on at valley point of GaN FET's drain voltage. So, EMI is improved and efficiency is higher too. V_{cspk} is controlled by V_{comp} and valley number is controlled by output load. When V_{comp} is higher than (V_{COMP_THDCM} + V_{COMP_THDCMHYS}), QR mode is enabled and valley number is 6th. As load increases, valley number decreases one by one until to the minimum value. When HV is lower than HV_{th_AChigh} and lasts for debounce time, AC low is declared and minimum valley number is 1th. When HV is higher than HV_{th_AChigh}, AC high is declared and minimum valley number is 2th, which is helpful to efficiency for lower switching loss at high input voltage.

Valley detect

Following waveform shows the method of valley detection. When falling edge of zero crossing voltage appears at ZCS pin, SY22812 will turn on GaN FET after some delay time.

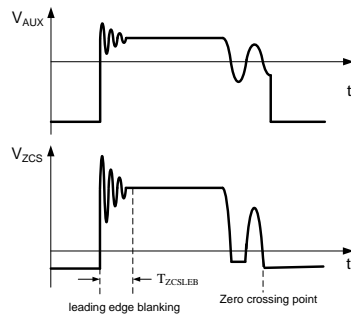


Fig.3 Valley detection

There is noise at ZCS pin when GaN FET turns off.

The noise may affect valley detection. SY22812 uses blanking time to avoid the noise, which will be described in the **Output OVP & UVP** section.

DCM mode

When V_{comp} is lower than V_{COMP_{TH}_DCM}, DCM mode is enabled. In DCM mode, V_{cspk} and switching frequency are all controlled by V_{comp}. PWM turns on at F_{sw} instant and won't wait for valley point. As load decreases, frequency firstly decreases from F_{LIMIT, DCM} to F_{MIN, DCM}, which is known as PFM mode. Light load efficiency is optimized for lower switching loss. When frequency has decreased to F_{MIN, DCM} and load goes on decreasing, V_{cspk} begins decreasing to keep constant voltage on output load.

Burst mode

When frequency and V_{cspk} have all decreased to minimum value, if output load keeps on decreasing, V_{comp} will be lower than V_{COMP_BURSTIN}. Then Burst mode is enabled. PWM will start when V_{comp} is higher than V_{COMP_BURSTSTART}. PWM number is controlled by T_{burst} in order to keep burst frequency lower than certain value. PWM won't stop until the number has been complete. Then PWM stops and wait for next rising edge of V_{COMP_BURSTSTART}. With this method, burst frequency is low and audible noise is optimized.

When V_{comp} is higher than V_{COMP_BURSTOUT}, SY22812 will enter DCM mode.

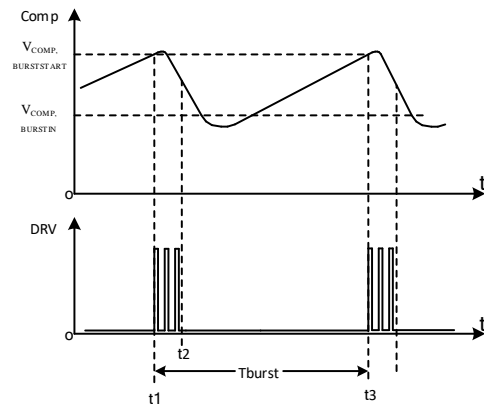


Fig.4 Quiet Burst

VCCH power supply

In order to simplify outside circuit, SY22812 contains VCCH pin. Maximum voltage of VCCH can be up to 140V. When Vcc is lower than V_{CC_REG}, VCCH will charge Vcc capacitor by inner circuit. When Vcc is higher than (V_{CC_REG} + V_{CC_REGHYS}), VCCH will stop charging.

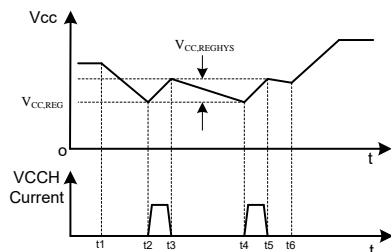


Fig.5 VCC Charge Function

If efficiency is important and BOM cost is ok, two windings can be used to reduce Vcc loss. In Fig.6, if Vout is low, Na3 voltage is too low and VCC charges Vcc. If Vout is high, Na3 voltage is high enough and VCC will be floating. A resistor and zener beside C11 are recommended, which can clamp high voltage coming from Na1's leakage inductance. R25 can be 1kOhm. D25's clamp voltage should be higher than Na1 voltage and be lower than C11's rating voltage.

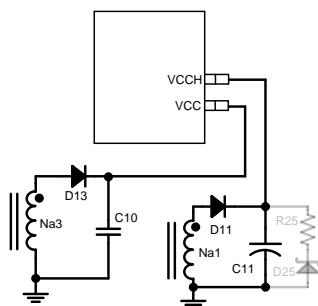


Fig.6 Typical Circuit for high efficiency application

Fig.7 shows one winding application. C10 can be as low as 1uF SMT capacitor. Resistor and zener diode beside C11 are not needed any more.

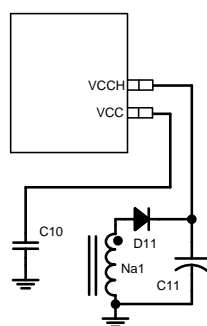


Fig.7 Typical Circuit for one winding application

During Xcap discharge process, voltage of C10 may be charged to Vcc_shunt. Then 35V capacitor is recommended.

Output over current protection (Iout_ ocp)

SY22812 detects output current at primary side. At PWM turn off instant, CS pin samples voltage on Rcs.

When current of Ns winding falls to zero, ZCS pin records demagnetization time. With these two signals, SY22812 calculates output current and the result is compared with Vref_ ocp. When the result is higher than Vref_ ocp for T_{IOUTOCP_DBC}, PWM stops and timer begins. After T_{ERROR}, logic will be reset and HV will charge Vcc to V_{CC_ON} for restart.

Iout_ ocp can be set by Rcs with following formula. Vref_ ocp is inner voltage of SY22812. Nps is Np/Ns of transformer. Rcs is R5 in following circuit.

$$I_{out_ocp} = 0.93 * \frac{V_{ref_ocp} * N_{ps}}{6 * R_{cs}}$$

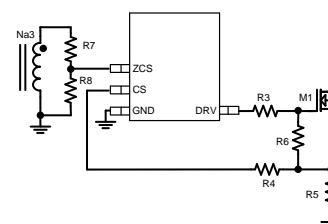


Fig.8 Rcs(R5) set for Iout_ ocp

SY22812 samples voltage on Rcs before PWM's falling edge. After a very short time, PWM turns off. Then M1 usually has turn off delay. So, sampled voltage is not real peak current of transformer. When input voltage becomes higher, the error will be greater too. SY22812 uses R4 to compensate the error. If Iout_ ocp becomes higher according to input voltage's increase, R4 should be added. If Iout_ ocp falls according to input voltage's increase, which means compensation is too much, R4 should be reduced.

Usually, M1 is GaN FET and turn off delay is little. R4 range may be 50ohm to 500ohm.

In quick charging applications, Vout range is usually very wide, such as 3.3V to 21V. Iout range is very wide too. SY22812 has two OCP options to adapt different applications.

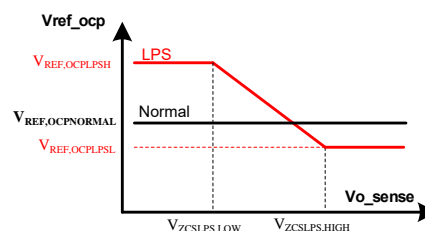


Fig.9 Two OCP options

The first example is as follows. Output includes 5V/3A, 9V/3A, 12V/3A, 15V/3A, 20V/3.25A, 3.3V-21V/3A. Normal OCP option is suitable. V_{REF,OCPNORMAL} is changeless according to different output voltages.

The second example is different. Output includes 5V/3A, 9V/3A, 10V/6.5A, 12V/5A, 15V/4A, 20V/3.25A, 5V-12V/5A. If normal OCP option is adopted, OCP value should be higher than 6.5A and may be set to 7.0A. When V_{out} is changed to 20V, I_{out_ocp} is still 7.0A and maximum output power will be 140W. This is forbidden in UL60950.

SY22812's LPS option is suitable for the second example. V_{REF_OCPLPS} is related to V_{out} . I_{out_ocp} can be set by R_{cs} when V_{out} is highest. When V_{out} is lower and V_{REF_OCPLPS} becomes higher. At $V_{out}=10V$, I_{out_ocp} is higher than 6.5A and 10V 6.5A won't trigger OCP.

LPS and Xcap selection by ZCS resistor

SY22812 has two options about output OCP. One is Normal option and the other is LPS option, which have been described in I_{out_ocp} section. Two options can be selected by ZCS resistor.

Meanwhile, X cap discharge function can be selected by ZCS resistor too. When Xcap is enabled, HV should be connected to AC side via two diodes. When Xcap is disabled, HV can be connected to Vbus to save BOM cost of the diodes.

Selection of ZCS resistors is as follows.

ZCS pull down (R_8)	Xcap function	I_{out_ocp}
25-27kOhm $\pm 1\%$	Disabled.	Normal Option
13.0kOhm $\pm 1\%$	Enabled.	Normal Option
7.5kOhm $\pm 1\%$	Disabled.	LPS Option
3.0-3.6kOhm $\pm 1\%$	Enabled.	LPS Option

ZCS_ovp threshold is 2.50V. When R_8 is determined, R_7 can be calculated according to V_{out_ovp} and N_a/N_s . Then CS in series resistor R_4 should be adjusted too. If I_{out_ocp} increases according to V_{ac} 's rising, value of R_4 should be increased for more compensation.

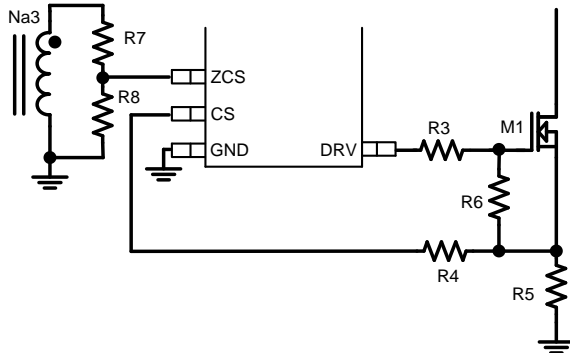


Fig.10 LPS and Xcap selection by ZCS resistor

Programmable drive current

At turn on instant, SY22812 uses constant current to charge C_{gs} of M1 and EMI performance is improved. At turn off instant, DRV pin will be fast pulled down to reduce turn off loss. Traditional drive resistors and diode are not needed. Only R_3 is used to adjust turn off speed slightly. Value of R_3 is recommended to be 5ohm-20ohm.

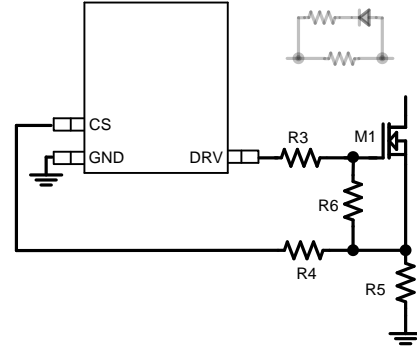


Fig.11 Drive circuit of GaN FET

At turn on instant, constant current value can be selected by R_6 . When current is lower, GaN's turn on speed will be slower and EMI performance will be better. Table is as follows. At SY22812's startup, R_6 is detected and current is fixed until startup again.

R_6	Constant current
10kohm	20mA
22kohm	10mA
43kohm	5mA
<2kohm	No PWM

Fig.12 Drive current table

Frequency Modulation

In QR mode, SY22812 adds triangle voltage on V_{cs} for frequency modulation. If Ring is 1-3, modulation amplitude is 20mV. If Ring is 4-6, modulation amplitude is 30mV in order to obtain effective range of frequency modulation.

Soft start

At start up, when V_{comp} rises to $V_{COMP_BURSTSTART}$, PWM starts and V_{cs} increases from minimum value linearly. Under heavy load or V_{out} short conditions, soft start will terminate after T_{SST} . Under light load or no-load conditions, when V_{cs} value determined by V_{comp} is lower than the value determined by soft start, soft start will terminate and V_{comp} will control V_{cs} .

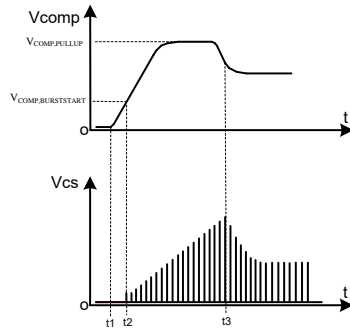


Fig.14 Soft start process

Under start up or Vout short conditions, Vout is very low and ZCS is the same. If ZCS cannot detect effective valley signal, Toff_max will be enabled. This is helpful to reduce deep CCM switching and voltage stress of SR MOS's Vds is optimized.

Vcs limit

After TCS_LEB2 in every cycle, when Vcs is higher than Vcs_limit, PWM will turn off immediately. It is cycle by cycle and won't affect next cycle's PWM On.

Vcs_max

Under normal working state, Vcs_limit can limit peak current of GaN and provide enough protection. When transformer's winding or secondary diode is short circuit, current slope is very high and transformer will enter saturation state. The current can rise to much higher level in TCS_LEB2.

SY22812 can detect Vcs after TCS_LEB1, which is shorter than TCS_LEB2. If Vcs is higher than VCS_MAX in 4 continuous cycles, PWM stops and timer begins. After TERROR, logic will be reset and HV will charge Vcc to VCC_ON for restart.

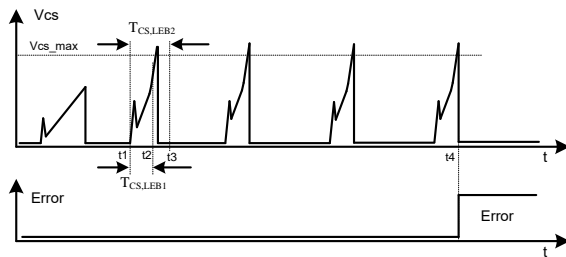


Fig.15 Vcs_max process

Brown out

When input voltage is lower than AC90V, current stress of transformer and primary GaN FET is very high. Heat stress is very high too. SY22812 has Brown out (BO) protection to protect power supply from broken down.

- BO: HV is lower than HVth_BO and last for TBO_DBC.

- BI: HV is higher than HVth_BI and last for TBI_DBC.

After BO, PWM stops and timer begins. After TERROR, logic will be reset and HV will charge Vcc to VCC_ON for restart.

X-cap discharge

Under light load, when charger is unplugged from AC socket, there may be remaining high voltage on input terminal, which is dangerous to be touched.

SY22812 uses HV to discharge X-cap. HV pin is connected to AC side through R1, D1 and D3. R1 is recommended to be 5k – 10kOhm, which can provide more reliability against surge voltage on AC line.

If HV hasn't rising edge for continuous TUNPLUG_DBC, AC unplug is detected. PWM stops and timer begins. HV sinks current of IHV_XCAP to Vcc pin. Vcc rises to VCC_SHUNT and HV falls linearly. When HV can't supply Vcc and Vcc is lower than VCC_OFF, discharge will stop.

Voltage rating of Vcc capacitor should be higher than Vcc_shunt. Then 35V capacitor is recommended.

During X-cap discharge, once HV detects rising edge, which means AC re-plug happens, the discharge will be terminated immediately. Timer of TERROR will go on. During TERROR, HV will keep Vcc between VCC_REG and (VCC_REG+VCC_REGHYS). After TERROR, logic will be reset and HV will charge Vcc to VCC_ON for restart.

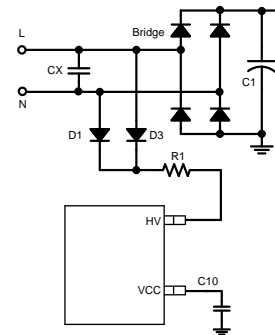


Fig.16 X-cap discharge circuit

Following waves show the process.

At t1, AC unplug happens.

At t2, AC unplug is confirmed. PWM stops and HV sinks current to Vcc.

At t3, Vcc rises to VCC_SHUNT.

At t4, X-cap discharge current is lower than Vcc's dissipation and Vcc begins falling.

At t5, Vcc is lower than VCC_OFF and discharge is reset.

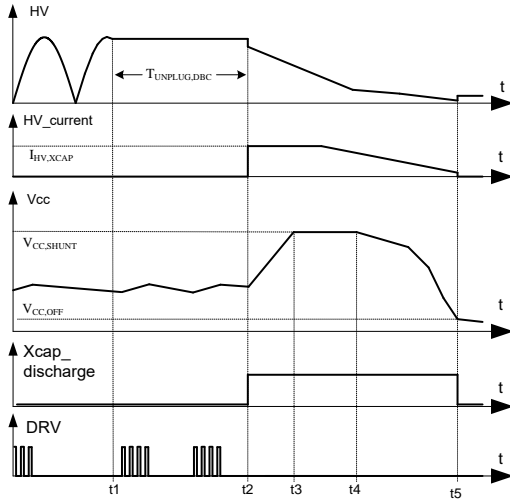


Fig.17 X-cap discharge waveforms

Output OVP & UVP

SY22812 detects output voltage through ZCS pin. When primary GaN FET turns off, there is a parasitic resonance on AUX winding. To avoid false trigger, blanking time is adopted, which is shown as follows. Blanking time is adaptive according to Vcspk. When Vcspk is 200mV, primary current is small and energy stored in leakage inductance is small too. Parasitic resonance on auxiliary winding will be shorter and blanking time can be shorter too. Blanking time rises to the maximum value along with Vcspk rising to 500mV.

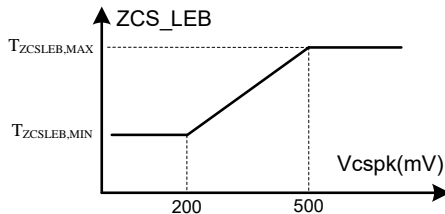


Fig.18 ZCS blanking time

When ZCS is higher than V_{ZCS_OVP} in continuous N_{ZCSOVP_DBC} cycles, ZCS_OVP is triggered. PWM stops and timer begins. After T_{ERROR}, logic will be reset and HV will charge Vcc to V_{CC_ON} for restart.

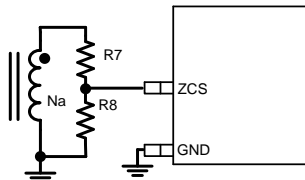


Fig.19 ZCS OVP setting

Output OVP threshold is calculated as below:

$$V_{out_ovp} = V_{zcs_ovp} * \frac{R7 + R8}{R8} * \frac{N_s}{N_a}$$

When ZCS is lower than V_{ZCS_UVP} in continuous time of T_{VOUTUVP_DBC}, ZCS_UVP is triggered. PWM stops and timer begins. After T_{ERROR}, logic will be reset and HV will charge Vcc to V_{CC_ON} for restart.

Note: Pull down resistor R8 should be determined firstly by LPS and Xcap selection. Then R7 is calculated according to above equation. UVP is used to avoid continuous working under Vout short circuit and is not necessary to be designed.

Vcc OVP

Vcc_ovp can prevent IC from damage due to abnormal high voltage when feedback loop is open or number of Na winding is wrong. When Vcc rises to V_{CC_SHUNT} and outside power's current ability is higher than shunt ability, Vcc can go on rising.

Vcc is detected all the time. If Vcc is higher than V_{CC_OVP} in continuous 4 cycles, Vcc_ovp is triggered. PWM stops and timer begins. After T_{ERROR}, logic will be reset and HV will charge Vcc to V_{CC_ON} for restart.

If the error condition still exists after restart, IC will work in hiccup mode.

Open Loop Protection

If output is short circuit, or opto-coupler open circuit, or load increase too much, Vcomp will be pulled up. When Vcomp is higher than V_{COMP_OLP} and last for T_{OLP_DBC}, OLP is triggered. PWM stops and timer begins. After T_{ERROR}, logic will be reset and HV will charge Vcc to V_{CC_ON} for restart.

Fault OTP & OVP

Fault pin can be used as OVP and OTP functions. Outside circuit is as follows. At normal state, current of Iotp is clamped by D12. D12's clamp voltage is between OTP threshold and OVP threshold. So, both protections won't be triggered.

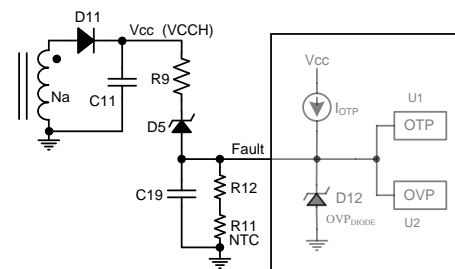


Fig.20 Fault OTP & OVP

Under error conditions, Vcc or VCCH will rise. D5 may be broken down. If pull up current is higher than D12's clamp ability, Fault voltage will be pulled up.

When Fault pin is higher than V_{OVP_TH} and last for $T_{FAULTTOTP/OVP_DBC}$, Fault_otp is triggered. PWM stops and timer begins. After T_{ERROR} , logic will be reset and HV will charge V_{cc} to V_{CC_ON} for restart.

R11 is NTC resistor. As temperature's rising, R11's resistance falls. When R11 is small enough, there will be no current flowing into D12 and all the current of I_{otp} will flow into R11. As I_{otp} is changeless, Fault voltage will fall along with R11's resistance. When Fault voltage is lower than V_{OTP_TH} , Fault_otp is triggered. PWM stops and timer begins. After T_{ERROR} , logic will be reset and HV will charge V_{cc} to V_{CC_ON} for restart. After restart, Fault pin is detected. PWM won't begin until Fault is higher than $V_{OTPEXIT_TH}$.

R9 is used to limit the current flowing into Fault pin. OVP threshold is mainly decided by D5's breakdown voltage. R12 is used to adjust OTP threshold conveniently. C19 is used to filter various noise and recommended value is 100pF.

CS pin short circuit

In Ton of every PWM, V_{cs} is detected at 4us and compared with V_{CS_SHORT} . If $V_{cs} < V_{CS_SHORT}$, short circuit protection is triggered. PWM stops and timer begins. After T_{ERROR} , logic will be reset and HV will charge V_{cc} to V_{CC_ON} for restart.

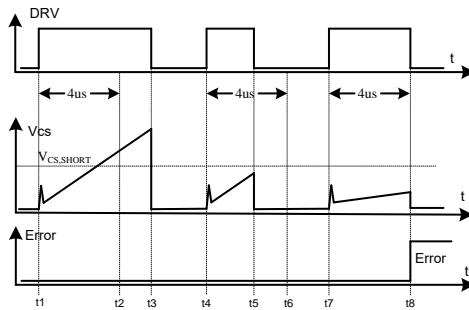


Fig.21 CS short protection

Above waveforms show the logic.

At t2, V_{cs} is higher than V_{CS_SHORT} . No protection.

At t5, Timer of 4us hasn't arrived.

No compare and no protection.

At t8, V_{cs} is lower than V_{CS_SHORT} at 4us.

Protection is triggered.

Internal OTP

SY22812 monitors die temperature under normal operating mode. Once die temperature rises above internal OTP threshold, PWM stops and timer begins. After T_{ERROR} , logic will be reset and HV will charge V_{cc} to V_{CC_ON} for restart.

Power Supply Design Guide

BUS capacitor calculation

Generally, bulk capacitor CBUS is selected according to the following rules.

- No PF: 1.5-1.8uF per watt (Output power).
- With PF: 0.5-0.8uF per watt (Output power).

Minimum BUS voltage calculation

Minimum BUS voltage appears when input voltage V_{ac} is lowest and output current reaches rated value. When there isn't PF circuit before Flyback, minimum BUS voltage is calculated as:

$$V_{BUS_MIN} = \sqrt{2V_{IN_MIN}^2 - \frac{P_o(1-K_{CH})}{\eta C_{BUS}f_o}}$$

K_{CH} is BUS capacitor charge coefficient (generally K_{CH} is set to 0.2~0.3). η is conversion efficiency and f_o is frequency of AC input.

Following examples are helpful to fast selection. AL Cap's actual capacitance is only 85-90% of its nominal value and capacitance has deviation in mass production. Following information is for reference only.

To 30W solution, there isn't Boost PFC circuit. Bus nominal capacitance is 27+27uF. V_{bus_min} is as follows.

Output Power	30W	35W	40W	45W
AC90V 50Hz	86V	80V	75V	68V
AC90V 60Hz	93V	87V	83V	78V

For better performance, V_{bus_min} should be higher than 80V.

To 66W solution, there isn't Boost PFC circuit. Under full load 20V3.3A, V_{bus_min} is as follows.

Bus nominal capacitance	82+22uF	82+10uF	82uF	68uF
AC90V 50Hz	82V	78V	72V	60V

For better performance, V_{bus_min} should be higher than 80V.

To 140W solution, topology is Boost + Flyback. Output is 28V 5A. Bus nominal capacitance is 39+39uF.

At AC90V 50Hz, Boost PFC outputs DC240V. V_{bus} is 222V(min) to 253V(max). Ripple is 31V.

At AC176V 50Hz, Boost PFC outputs DC350V. V_{bus} is 338V(min) to 362V(max). Ripple is 24V.

Transformer parameter calculation

1) Primary/secondary turns ratio: NPS

NPS is limited by voltage stress of primary GaN FET:

$$N_{PS} \leq \frac{V_{MOS_BR} K_{DR} - \sqrt{2} V_{IN_MAX} - \Delta V_{SN}}{V_O + V_{D_F}}$$

V_{MOS_BR} is the breakdown voltage of primary GaN FET;

K_{DR} is VDS de-rating factor of power MOS;

V_{IN_MAX} is always AC264V;

V_{D_F} is forward voltage of secondary rectification diode; If SR is adopted at secondary side, V_{D_F} is equal to 0.

ΔV_{SN} is voltage spike at primary GaN turn off. Starting value can be 50V.

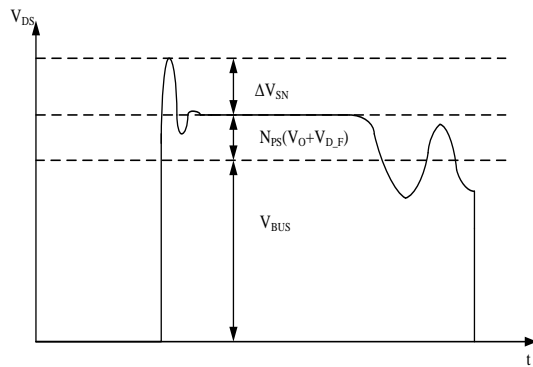


Fig.22 Primary Vds waveform

When N_{PS} is determined, reflect voltage can be calculated as follows.

$$V_{OR} = N_{PS} * (V_O + V_{D_F})$$

2) Primary inductance: LP

SY22812 has QR/DCM mode and CCM is not available. Transformer primary inductance is mainly related with switching frequency. When V_{bus} is the minimum value, L_p can be calculated by following formula.

$$L_p = \frac{1}{2 * F_{SW_MIN} * V_O * I_O} * \left(\frac{V_{BUS_MIN} * V_{OR}}{V_{BUS_MIN} + V_{OR}} \right)^2$$

V_O : Output voltage and unit is V.

N_{PS} : Primary/secondary turns ratio without unit.

V_{bus_min} : Minimum voltage after bridge and unit is V.

F_{sw_min} : Frequency at V_{bus_min} and unit is kHz.

I_O : Output current and unit is A.

L_p : Primary inductance and unit is mH.

In the parameters, V_O , N_{PS} , V_{bus_min} and I_O have been determined. Only F_{sw_min} needs to be selected. When F_{sw_min} is higher, L_p will be smaller. The frequency at AC230V will be higher too.

To typical application, F_{sw_min} is about 100-130kHz, which is at V_{bus_min} (usually 80-90V). Then frequency at V_{bus_max} (370V) is about 160-220kHz.

3) Turns of primary winding: Np

(a) Select the magnetic core, confirm the effective AE

(b) Preset B_{max} of magnetic core (0.32T~0.36T)

(c) Calculate primary R_{CS}

$$R_{CS} = 0.93 * \frac{V_{ref_ocp} * N_{PS}}{6 * I_{out_ocp}}$$

In normal option, V_{ref_ocp} is $V_{REF_OCPNORMAL}$.

In LPS option, V_{ref_ocp} is $V_{REF_OCPLPSL}$.

(d) Calculate maximum primary peak current

$$I_{PPK_MAX} = \frac{V_{CS_LIMIT}}{R_{CS}}$$

(e) Calculate primary turns: N_P

$$N_P = \frac{L_P * I_{PPK_MAX}}{B_{MAX} * A_E}$$

4) Turns of secondary winding: NS

$$N_S = \frac{N_P}{N_{PS}}$$

In actual design, F_{sw_min} is difficult to be determined. If a random value is selected, later calculation may be hard and this may be unsuitable to the bobbin of transformer. So design procedure is always as follows, which is inverse to traditional method.

Select transformer and AE ->

Determine winding width of bobbin ->

Select N_S wire -> Determine N_S ->

Determine V_{OR} and N_{PS} -> Calculate N_P ->

Select N_P wire -> Calculate R_{CS} ->

Calculate I_{ppk_max} -> Determine B_{max} ->

Calculate L_p at last.

With this procedure, F_{sw_min} is not an input parameter. When L_p is calculated, switching frequency F_{sw} is determined too. This will always



lead to a satisfactory design and efficiency will always be close to highest value for certain transformer. It is not needed to try again and again.

5) Turns of auxiliary winding: NA

To fast charge application, Vout range is wide. Turns of AUX winding should take Vout_max and Vout_min into consideration.

If efficiency is important and BOM cost is ok, two AUX windings are recommended.

- AUXL can supply Vcc at Vout_max.

$$18V < \frac{V_{OUT_MAX}}{N_S} * N_{AUXL} < 22V$$

- AUXH can supply Vcc at Vout_min.

$$10V < \frac{V_{OUT_MIN}}{N_S} * N_{AUXH} < 14V$$

If BOM cost is important, one winding is enough, which is AUXH. Turns of AUXH winding is the same as N_{AUXH} in above formula.

Secondary MOSFET Selection

Under the conditions of Vbus_max and Vout_ovp, the reverse voltage of secondary rectification MOSFET will reach maximum level. The maximum voltage (ignore voltage spike when primary MOS is turned on) is calculated as follows.

$$V_{D_R_MAX} = \frac{\sqrt{2}V_{IN_MAX}}{N_{PS}} + V_{O_OVP}$$

Maximum instantaneous forward current is calculated as equation below:

$$I_{SPK_MAX} = I_{PPK_MAX} * N_{PS}$$

To a 66W (20V 3.3A) solution, BSC098N10NS5 is recommended, which is 100V 8.2mOhm (Vgs=10V).

To a 90W (20V 4.5A) solution, BSC0805LS is recommended, which is 100V 6.0mOhm (Vgs=10V).

To a 120W (20V 6.0A) solution, two MOSFETs in parallel is recommended, which is mainly for heat sink consideration. BSC098N10NS5 is ok, which is 100V 8.2mOhm (Vgs=10V).

MOS selection is related to heat dissipation design.

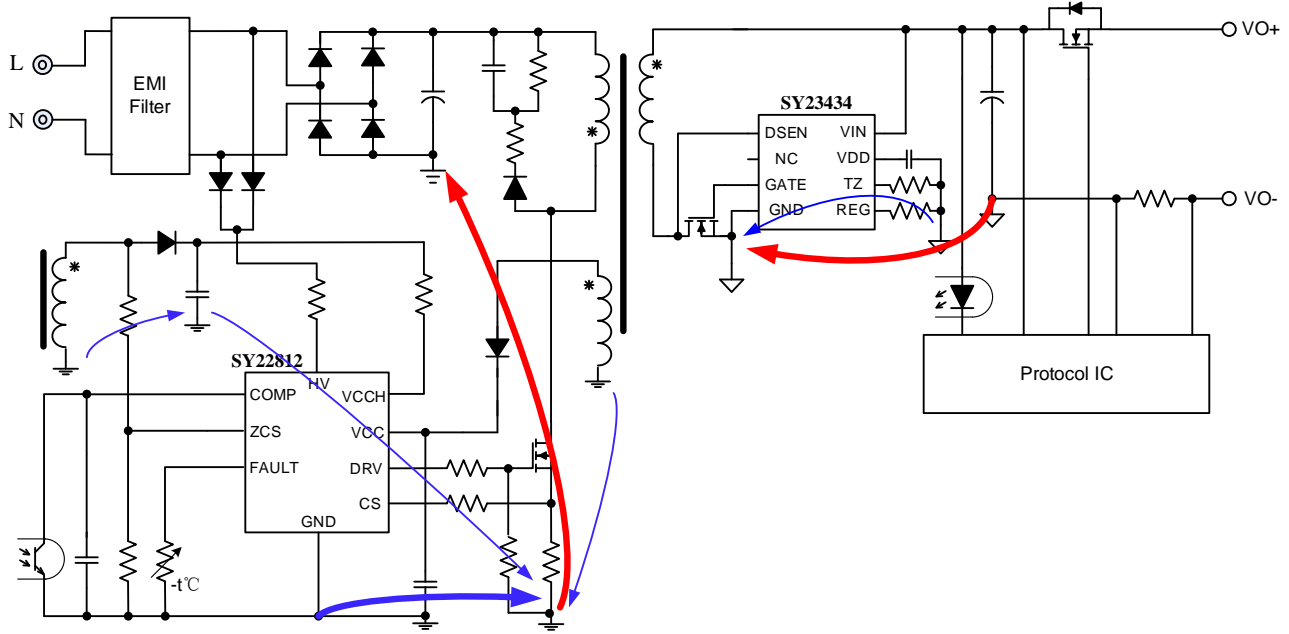
Place refer to actual temperature test.

Layout Considerations

Following rules is recommended for normal working and EMI considerations.

- Switching node: Primary Drain/AUX/Core;
Secondary Drain/AUX/Core.
- Important signal node (easy to be disturbed):
Primary: Vcs, Fault, Comp, ZCS and Fmax etc.
Secondary: REG, TZ and Feedback loop etc.
- In order to guarantee normal working, important signal node should be far away from switching node. If PCB routing is hard, static node should be used as shielding between switching and signal node. Static node can be Vbus, GND, Vcc, VCCH and Vout, SGND etc.
- In order to realize good EMI performance, switching node on PCB layout should be as small as possible. Switching node should not be selected as heat sink method, such as GaN's drain.
- In order to realize good EMI performance, main current loop should be as small as possible.
 - Current in Ton: Bus cap -> transformer -> GaN -> Rcs -> GND -> Bus cap.
 - Current in Toff: Transformer -> SR_MOS -> Cout -> GND -> Transformer.
 - Current in leakage inductance and snubber circuit.
 - Drive loop of primary and secondary MOS.
- These components should be closed to SY22812. Fault capacitor, Comp Capacitor, Fmax resistor, CS resistor (in series), Vcc capacitor.

ZCS pull up resistor should be placed at AUX pin of transformer and pull-down resistor should be closed to ZCS pin.
- These components should be closed to SY23434. REG resistor, TZ resistor, Vdd capacitor and Vin capacitor.
- GND routing is as follows.
SY22812's GND should be connected to Rcs-GND in order to get accurate Vcs signal.



As $V_{gs(th)}$ of GaN FET is as low as 1.2V, it is easy to be falsely triggered by noise.

- IC_GND should be connected to Rcs_GND directly.
- Drive loop should be as small as possible.

Design Example

A design example of typical application is shown below step by step.

Input/output specification

Parameter	Symbol	Value
Input voltage range	V_{IN}	90V~264V
Rated output power	P_O	66W
Rated output voltage	V_O	5V - 20V
Output OVP level	$V_{O,OVp}$	24V
Rated output current	I_O	3.3A
OCP	I_{OCP}	3.68A
Efficiency	η	93%

Preset parameter

Parameter	Symbol	Value
Break down voltage of power FET	$V_{MOS,BR}$	650V
V_{DS} de-rating factor of power FET	K_{DR}	90%
Spike on V_{DS} at power FET turn off	ΔV_{SN}	70V
BUS capacitor charge coefficient	K_{CH}	0.2
Secondary diode forward voltage drop	$V_{D,R}$	0V
Transformer effective Ae (RM8)	A_E	62 mm ²

1) BUS capacitor selection

Select BUS capacitor: $C_{BUS}=104\mu F$ (1.57uF/W)

2) Minimum BUS voltage calculation

BUS capacitor charge coefficient: $K_{CH}=0.2$

$$V_{BUS_MIN} = \sqrt{2V_{IN_MIN}^2 - \frac{P_O(1-K_{CH})}{\eta C_{BUS} f_o}} = \sqrt{2 \times 90^2 - \frac{66 \times (1-0.2)}{93\% \times 104 \mu \times 60}} = 84V$$

3) Transformer design

(a) Calculate primary/secondary turns ratio: N_{PS}

$$N_{PS} \leq \frac{V_{MOS_BR} K_{DR} - \sqrt{2} V_{IN_MAX} - \Delta V_{SN}}{V_O + V_{D_F}} = \frac{650 \times 0.9 - \sqrt{2} \times 264 - 70}{20 + 0} = 7.1$$

N_{PS} is selected to: $N_{PS}=6.25$, Reflect voltage $V_{OR}=6.25 \times 20V=125V$.

(b) Calculate L_p of transformer: Select $F_{sw_min}=110kHz$

$$L_p = \frac{1}{2 * F_{SW_MIN} * V_O * I_O} * \left(\frac{V_{BUS_MIN} * V_{OR}}{V_{BUS_MIN} + V_{OR}} \right)^2 = \frac{1}{2 * 110kHz * 20V * 3.3A} * \left(\frac{84 * 125}{84 + 125} \right)^2 = 0.174mH$$

(c) Calculate R_{CS} : In normal option, $V_{ref_ocp}=0.555V$.

$$R_{CS} = \frac{0.93 * V_{REF_OCP} * N_{PS}}{6 * I_{OUT_OCP}} = \frac{0.93 * 0.555 * 6.25}{6 * 3.68} = 0.146\Omega$$

(d) Calculate maximum primary peak current:

$$I_{PPK_MAX} = \frac{V_{CS_LIMITL}}{R_{CS}} = \frac{0.50}{0.146} = 3.42A$$

(e) Calculate primary winding turns N_p : $B_{MAX}=0.27T$

$$N_p = \frac{L_p * I_{PPK_MAX}}{B_{MAX} * A_E} = \frac{170\mu H * 3.42A}{0.37T * 62mm^2} = 25.3ts$$

(f) Calculate secondary winding turns: N_s

$$N_s = \frac{N_p}{N_{ps}} = \frac{25}{6.25} = 4$$

(g) Calculate auxiliary winding turns $N_{AUXL}=4ts$: $V_{out_max}=20V$

$$18V < \frac{V_{OUT_MAX}}{N_s} * N_{AUXL} < 22V, \quad \text{So, } 3.6 < N_{AUXL} < 4.4$$

Calculate auxiliary winding turns $N_{AUXH}=10ts$: $V_{out_min}=5V$

$$10V < \frac{V_{OUT_MIN}}{N_s} * N_{AUXL} < 14V, \quad \text{So, } 8 < N_{AUXH} < 11.2$$

5) Secondary diode selection

(a)Maximum reverse voltage calculation:

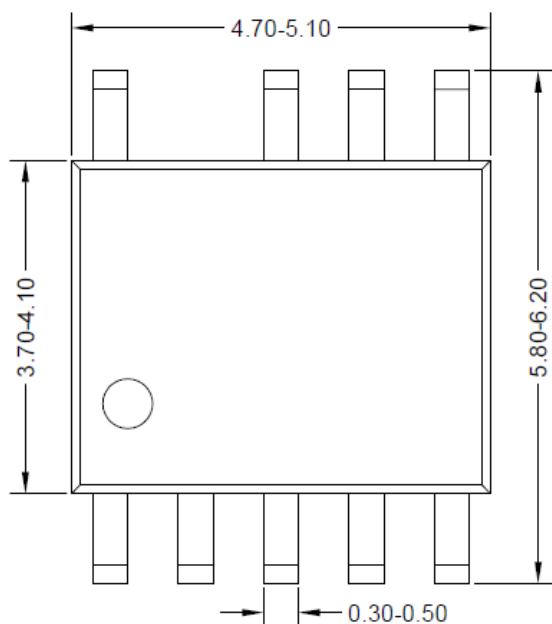
$$V_{D_R_MAX} = \frac{\sqrt{2}V_{IN_MAX}}{N_{ps}} + V_{O_OVP} = \frac{\sqrt{2} \times 264}{6.25} + 24 = 84V$$

Considering the voltage spike, reverse voltage rating is recommended to be 100V~120V.

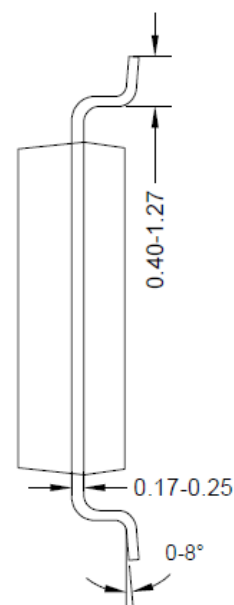
(b) Maximum instantaneous forward current:

$$I_{SPK_MAX} = I_{PPK_MAX} * N_{ps} = 3.42A * 6.25 = 21.4A$$

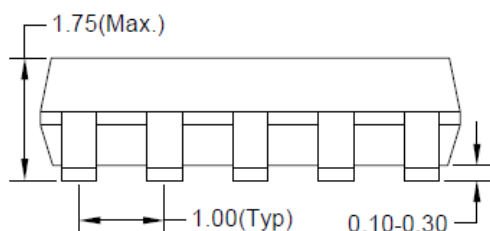
SSOP9 Package Outline Drawing



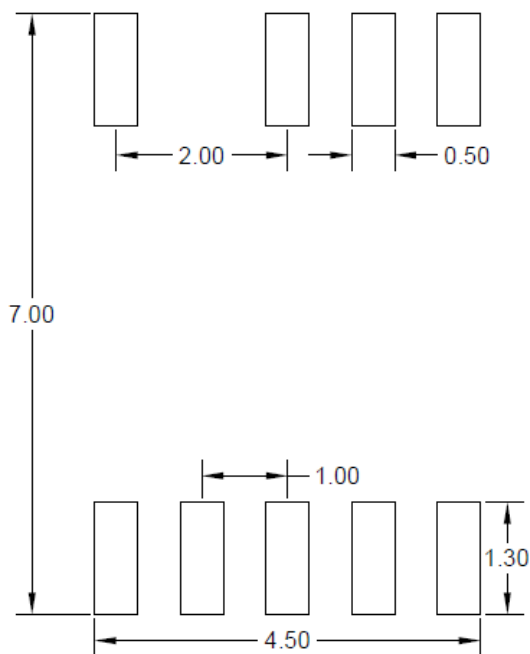
Top view



Side view



Front view

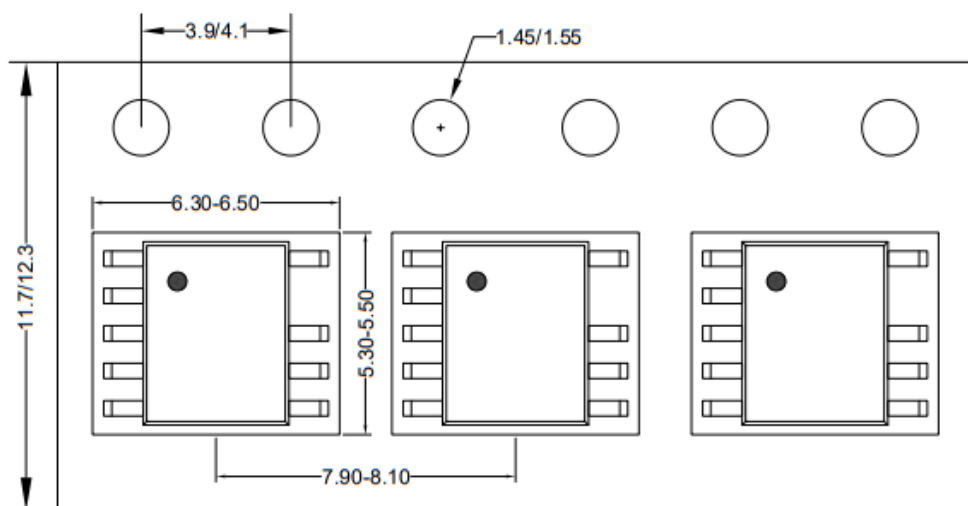


Recommended PCB layout
 (Reference only)

Notes: All dimension in millimeter and exclude mold flash & metal burr.

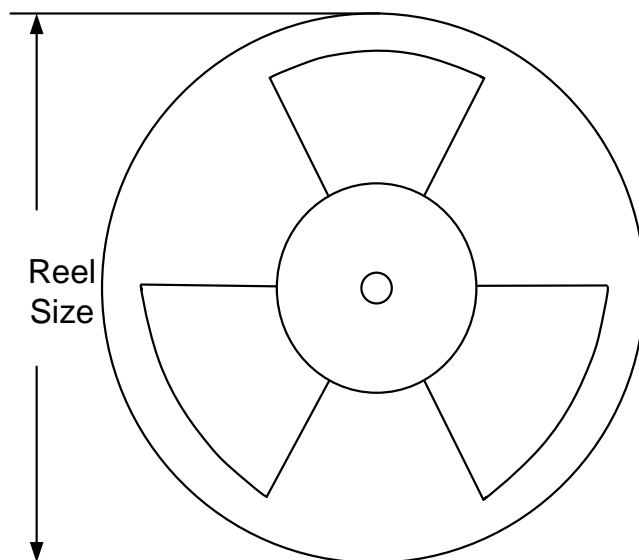
Taping & Reel Specification

1. Taping Orientation



Feeding Direction →

2. Carrier Tape & Reel specification for packages



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer * length(mm)	Leader * length (mm)	Qty per reel (pcs)
SSOP9	12	8	13"	400	400	4000

Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

Date	Revision	Change
May 25, 2023	Revision 0.9	Initial Release

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